

MM74HC373

3-STATE Octal D-Type Latch

General Description

The MM74HC373 high speed octal D-type latches utilize advanced silicon-gate CMOS technology. They possess the high noise immunity and low power consumption of standard CMOS integrated circuits, as well as the ability to drive 15 LS-TTL loads. Due to the large output drive capability and the 3-STATE feature, these devices are ideally suited for interfacing with bus lines in a bus organized system.

When the LATCH ENABLE input is HIGH, the Q outputs will follow the D inputs. When the LATCH ENABLE goes LOW, data at the D inputs will be retained at the outputs until LATCH ENABLE returns HIGH again. When a high logic level is applied to the OUTPUT CONTROL input, all outputs go to a high impedance state, regardless of what signals are present at the other inputs and the state of the storage elements.

The 74HC logic family is speed, function, and pin-out compatible with the standard 74LS logic family. All inputs are protected from damage due to static discharge by internal diode clamps to V_{CC} and ground.

Features

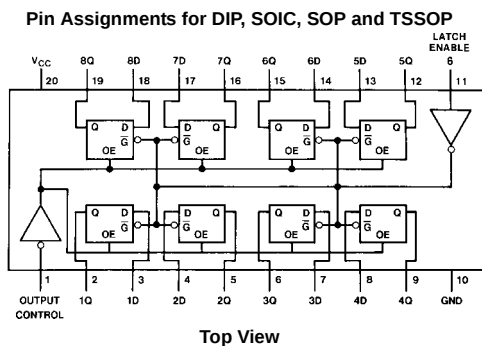
- Typical propagation delay: 18 ns
- Wide operating voltage range: 2 to 6 volts
- Low input current: 1 μ A maximum
- Low quiescent current: 80 μ A maximum (74 Series)
- Output drive capability: 15 LS-TTL loads

Ordering Code:

Order Number	Package Number	Package Description
MM74HC373WM	M20B	20-Lead Small Outline Integrated Circuit (SOIC), JEDEC MS-013, 0.300" Wide
MM74HC373SJ	M20D	20-Lead Small Outline Package (SOP), EIAJ TYPE II, 5.3mm Wide
MM74HC373MTC	MTC20	20-Lead Thin Shrink Small Outline Package (TSSOP), JEDEC MO-153, 4.4mm Wide
MM74HC373N	N20A	20-Lead Plastic Dual-In-Line Package (PDIP), JEDEC MS-001, 0.300" Wide

Devices also available in Tape and Reel. Specify by appending the suffix letter "X" to the ordering code.

Connection Diagram



Truth Table

Output Control	Latch Enable	Data	373 Output
L	H	H	H
L	H	L	L
L	L	X	Q_0
H	X	X	Z

H = HIGH Level

L = LOW Level

Q_0 = Level of output before steady-state input conditions were established.

Z = High Impedance

Absolute Maximum Ratings(Note 1)

(Note 2)

Supply Voltage (V_{CC})	-0.5 to +7.0V
DC Input Voltage (V_{IN})	-1.5 to $V_{CC} + 1.5V$
DC Output Voltage (V_{OUT})	-0.5 to $V_{CC} + 0.5V$
Clamp Diode Current (I_{IK}, I_{OK})	± 20 mA
DC Output Current, per pin (I_{OUT})	± 35 mA
DC V_{CC} or GND Current, per pin (I_{CC})	± 70 mA
Storage Temperature Range (T_{STG})	-65°C to +150°C
Power Dissipation (P_D)	
(Note 3)	600 mW
S.O. Package only	500 mW
Lead Temperature (T_L)	
(Soldering 10 seconds)	260°C

Recommended Operating Conditions

	Min	Max	Units
Supply Voltage (V_{CC})	2	6	V
DC Input or Output Voltage (V_{IN}, V_{OUT})	0	V_{CC}	V
Operating Temperature Range (T_A)	-40	+85	°C
Input Rise or Fall Times (t_r, t_f) $V_{CC} = 2.0V$		1000	ns
$V_{CC} = 4.5V$		500	ns
$V_{CC} = 6.0V$		400	ns

Note 1: Absolute Maximum Ratings are those values beyond which damage to the device may occur.

Note 2: Unless otherwise specified all voltages are referenced to ground.

Note 3: Power Dissipation temperature derating — plastic "N" package: -12 mW/°C from 65°C to 85°C.

DC Electrical Characteristics

Symbol	Parameter	Conditions	V _{CC}	T _A = 25°C		T _A = −40 to 85°C		T _A = −55 to 125°C		Units
				Typ	Guaranteed Limits					
V _{IH}	Minimum HIGH Level Input Voltage		2.0V		1.5	1.5	1.5	V		
			4.5V		3.15	3.15	3.15	V		
			6.0V		4.2	4.2	4.2	V		
V _{IL}	Maximum LOW Level Input Voltage		2.0V		0.5	0.5	0.5	V		
			4.5V		1.35	1.35	1.35	V		
			6.0V		1.8	1.8	1.8	V		
V _{OH}	Minimum HIGH Level Output Voltage	V _{IN} = V _{IH} or V _{IL} I _{OUT} ≤ 20 μA	2.0V	2.0	1.9	1.9	1.9	V		
			4.5V	4.5	4.4	4.4	4.4	V		
			6.0V	6.0	5.9	5.9	5.9	V		
		V _{IN} = V _{IH} or V _{IL} I _{OUT} ≤ 6.0 mA I _{OUT} ≤ 7.8 mA	4.5V	4.2	3.98	3.84	3.7	V		
			6.0V	5.7	5.48	5.34	5.2	V		
V _{OL}	Maximum LOW Level Output Voltage	V _{IN} = V _{IH} or V _{IL} I _{OUT} ≤ 20 μA	2.0V	0	0.1	0.1	0.1	V		
			4.5V	0	0.1	0.1	0.1	V		
			6.0V	0	0.1	0.1	0.1	V		
		V _{IN} = V _{IH} or V _{IL} I _{OUT} ≤ 6.0 mA I _{OUT} ≤ 7.8 mA	4.5V	0.2	0.26	0.33	0.4	V		
			6.0V	0.2	0.26	0.33	0.4	V		
I _{IN}	Maximum Input Current	V _{IN} = V _{CC} or GND	6.0V		±0.1	±1.0	±1.0	μA		
I _{OZ}	Maximum 3-STATE Output Leakage Current	V _{IN} = V _{IH} or V _{IL} , OC = V _{IH} V _{OUT} = V _{CC} or GND	6.0V		±0.5	±5	±10	μA		
I _{CC}	Maximum Quiescent Supply Current	V _{IN} = V _{CC} or GND I _{OUT} = 0 μA	6.0V		8.0	80	160	μA		

Note 4: For a power supply of $5V \pm 10\%$ the worst case output voltages (V_{OH} and V_{OL}) occur for HC at 4.5V. Thus the 4.5V values should be used when designing with this supply. Worst case V_{IH} and V_{IL} occur at $V_{CC} = 5.5V$ and 4.5V respectively. (The V_{IH} value at 5.5V is 3.85V.) The worst case leakage current (I_{IN} , I_{CC} , and I_{OZ}) occur for CMOS at the higher voltage and so the 6.0V values should be used.

AC Electrical Characteristics $V_{CC} = 5V$, $T_A = 25^\circ C$, $t_r = t_f = 6\text{ ns}$

Symbol	Parameter	Conditions	Typ	Guaranteed Limit	Units
t_{PHL} , t_{PLH}	Maximum Propagation Delay, Data to Q	$C_L = 45\text{ pF}$	18	25	ns
t_{PHL} , t_{PLH}	Maximum Propagation Delay, LE to Q	$C_L = 45\text{ pF}$	21	30	ns
t_{PZH} , t_{PZL}	Maximum Output Enable Time	$R_L = 1\text{ k}\Omega$ $C_L = 45\text{ pF}$	20	28	ns
t_{PHZ} , t_{PLZ}	Maximum Output Disable Time	$R_L = 1\text{ k}\Omega$ $C_L = 5\text{ pF}$	18	25	ns
t_S	Minimum Set Up Time			5	ns
t_H	Minimum Hold Time			10	ns
t_W	Minimum Pulse Width		9	16	ns

AC Electrical Characteristics $V_{CC} = 2.0\text{--}6.0V$, $C_L = 50\text{ pF}$, $t_r = t_f = 6\text{ ns}$ (unless otherwise specified)

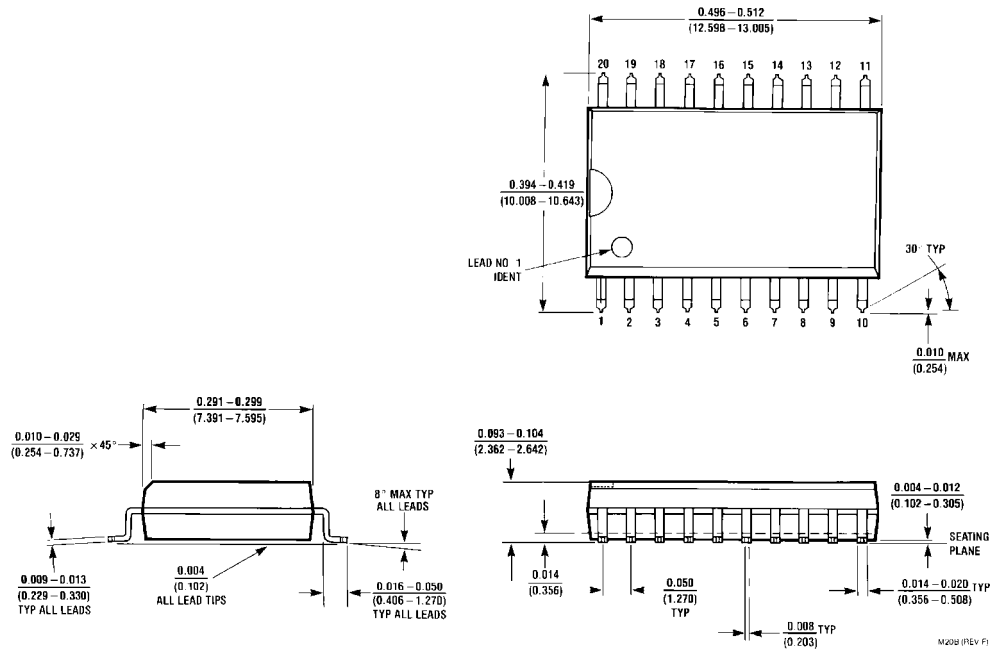
Symbol	Parameter	Conditions	V _{CC}	T _A = 25°C		T _A = -40 to 85°C	T _A = -55 to 125°C	Units
				Typ	Guaranteed Limits			
t _{PHL} , t _{PLH}	Maximum Propagation Delay, Data to Q	C _L = 50 pF	2.0V	50	150	188	225	ns
		C _L = 150 pF	2.0V	80	200	250	300	ns
		C _L = 50 pF	4.5V	22	30	37	45	ns
		C _L = 150 pF	4.5V	30	40	50	60	ns
		C _L = 50 pF	6.0V	19	26	31	39	ns
t _{PHL} , t _{PLH}	Maximum Propagation Delay, LE to Q	C _L = 50 pF	2.0V	63	175	220	263	ns
		C _L = 150 pF	2.0V	110	225	280	338	ns
		C _L = 50 pF	4.5V	25	35	44	52	ns
		C _L = 150 pF	4.5V	35	45	56	68	ns
		C _L = 50 pF	6.0V	21	30	37	45	ns
t _{PZH} , t _{PZL}	Maximum Output Enable Time	R _L = 1 kΩ						
		C _L = 50 pF	2.0V	50	150		225	ns
		C _L = 150 pF	2.0V	80	200	250	300	ns
		C _L = 50 pF	4.5V	21	30	37	45	ns
		C _L = 150 pF	4.5V	30	40	50	60	ns
t _{PHZ} , t _{PLZ}	Maximum Output Disable Time	C _L = 50 pF	6.0V	19	26	31	39	ns
		C _L = 150 pF	6.0V	26	35	44	53	ns
		R _L = 1 kΩ	2.0V	50	150	188	225	ns
		C _L = 50 pF	4.5V	21	30	37	45	ns
			6.0V	19	26	31	39	ns
t _S	Minimum Set Up Time		2.0V		50	60	75	ns
			4.5V		9	13	15	ns
			6.0V		9	11	13	ns
t _H	Minimum Hold Time		2.0V		5	5	5	ns
			4.5V		5	5	5	ns
			6.0V		5	5	5	ns
t _W	Minimum Pulse Width		2.0V	30	80	100	120	ns
			4.5V	10	16	20	24	ns
			6.0V	9	14	18	20	ns
t _{THL} , t _{TLH}	Maximum Output Rise and Fall Time	C _L = 50 pF	2.0V	25	60	75	90	ns
			4.5V	7	12	15	18	ns
			6.0V	6	10	13	15	ns
C _{PD}	Power Dissipation Capacitance (Note 5)	(per latch) OC = V _{CC} OC = GND		30 50				pF pF
C _{IN}	Maximum Input Capacitance			5	10	10	10	pF

AC Electrical Characteristics (Continued)

Symbol	Parameter	Conditions	V _{CC}	T _A = 25°C	T _A = -40 to 85°C	T _A = -55 to 125°C	Units
				Typ	Guaranteed Limits		
C _{OUT}	Maximum Output Capacitance			15	20	20	pF

Note 5: C_{PD} determines the no load dynamic power consumption, $P_D = C_{PD} V_{CC}^2 f + I_{CC} V_{CC}$, and the no load dynamic current consumption, $I_S = C_{PD} V_{CC} f + I_{CC}$.

Physical Dimensions inches (millimeters) unless otherwise noted



20-Lead Small Outline Integrated Circuit (SOIC), JEDEC MS-013, 0.300" Wide
Package Number M20B

Physical Dimensions inches (millimeters) unless otherwise noted (Continued)



LAND PATTERN RECOMMENDATION

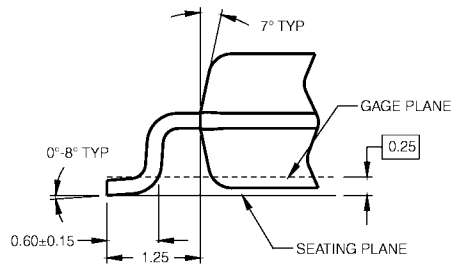


DIMENSIONS ARE IN MILLIMETERS

NOTES:

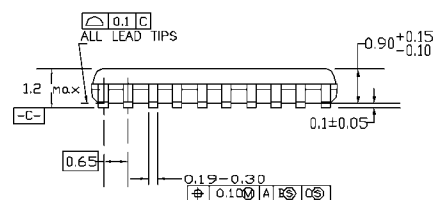
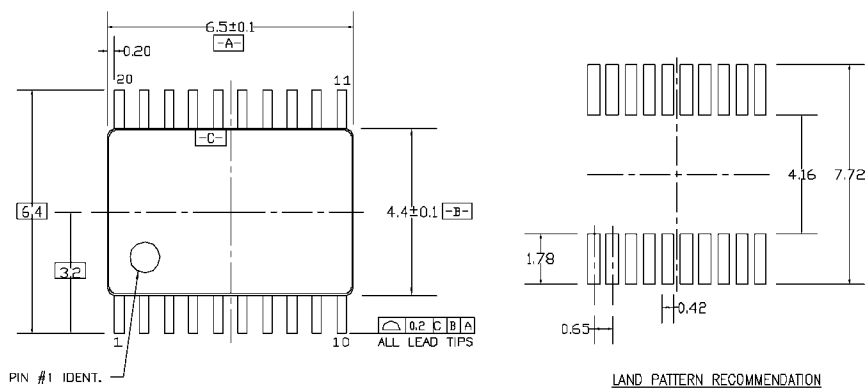
- CONFORMS TO EIAJ EDR-7320 REGISTRATION, ESTABLISHED IN DECEMBER, 1998.
- DIMENSIONS ARE IN MILLIMETERS.
- DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSIONS.

M20DRevB1



DETAIL A

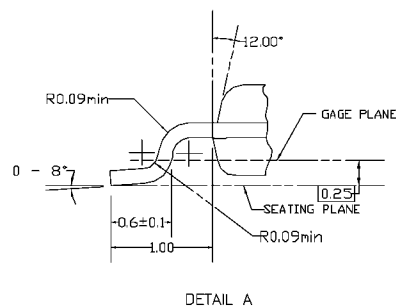
**20-Lead Small Outline Package (SOP), EIAJ TYPE II, 5.3mm Wide
Package Number M20D**

Physical Dimensions inches (millimeters) unless otherwise noted (Continued)


DIMENSIONS ARE IN MILLIMETERS

NOTES:

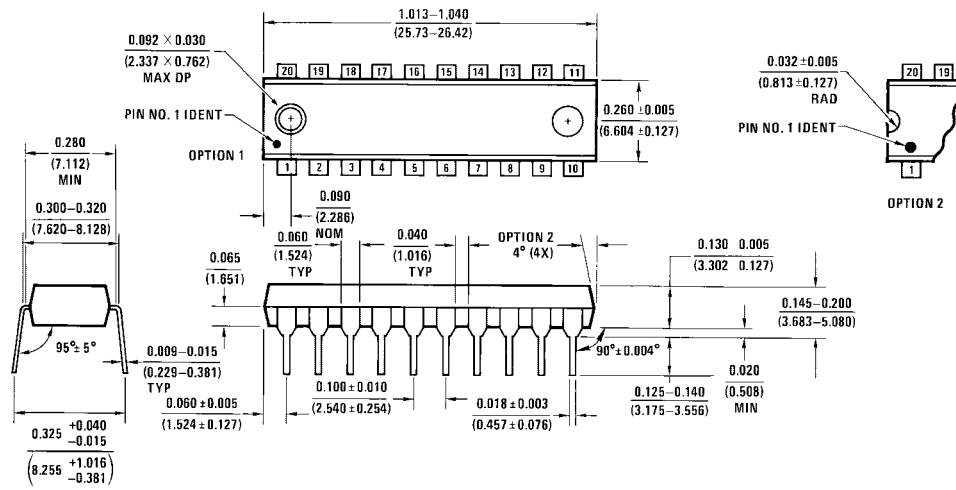
- CONFORMS TO JEDEC REGISTRATION MO-153, VARIATION AC, REF NOTE 6, DATE 7/93.
- DIMENSIONS ARE IN MILLIMETERS.
- DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLDS FLASH, AND TIE BAR EXTRUSIONS.
- DIMENSIONS AND TOLERANCES PER ANSI Y14.5M, 1982.



MTC20REVD1

**20-Lead Thin Shrink Small Outline Package (TSSOP), JEDEC MO-153, 4.4mm Wide
Package Number MTC20**

Physical Dimensions inches (millimeters) unless otherwise noted (Continued)



N20A (REV G)

20-Lead Plastic Dual-In-Line Package (PDIP), JEDEC MS-001, 0.300" Wide
Package Number N20A

Fairchild does not assume any responsibility for use of any circuitry described, no circuit patent licenses are implied and Fairchild reserves the right at any time without notice to change said circuitry and specifications.

LIFE SUPPORT POLICY

FAIRCHILD'S PRODUCTS ARE NOT AUTHORIZED FOR USE AS CRITICAL COMPONENTS IN LIFE SUPPORT DEVICES OR SYSTEMS WITHOUT THE EXPRESS WRITTEN APPROVAL OF THE PRESIDENT OF FAIRCHILD SEMICONDUCTOR CORPORATION. As used herein:

1. Life support devices or systems are devices or systems which, (a) are intended for surgical implant into the body, or (b) support or sustain life, and (c) whose failure to perform when properly used in accordance with instructions for use provided in the labeling, can be reasonably expected to result in a significant injury to the user.
2. A critical component in any component of a life support device or system whose failure to perform can be reasonably expected to cause the failure of the life support device or system, or to affect its safety or effectiveness.

www.fairchildsemi.com